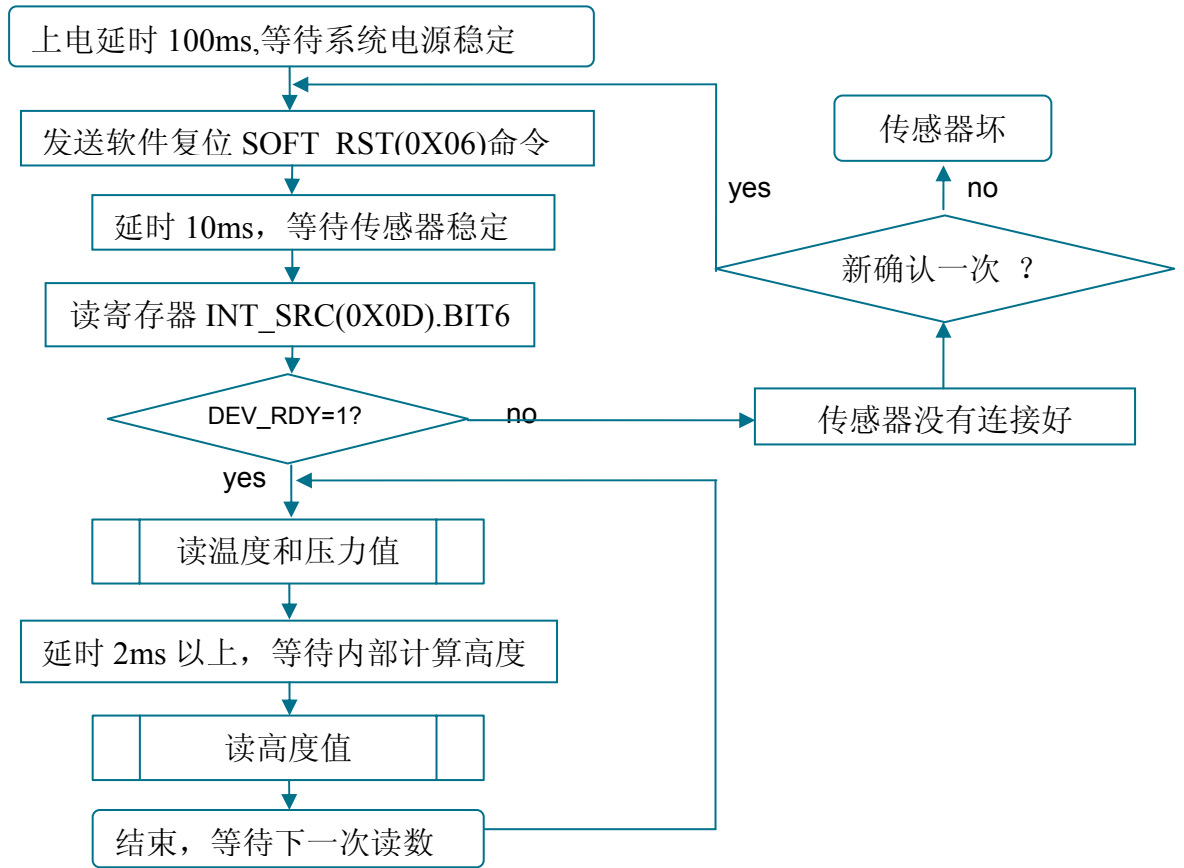
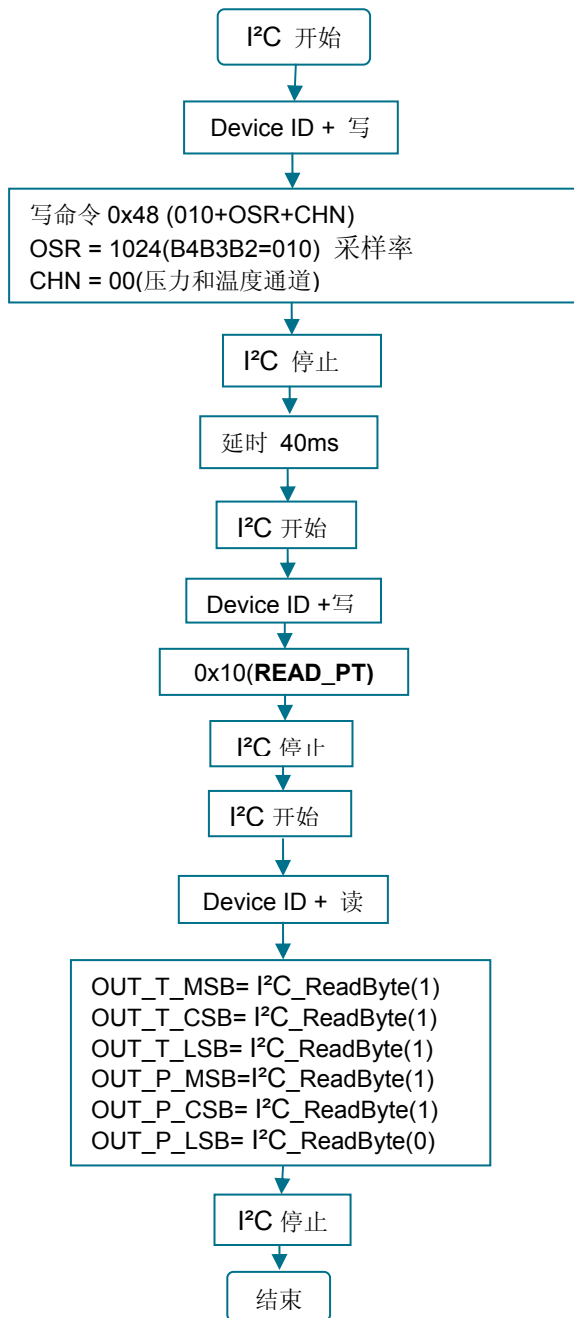


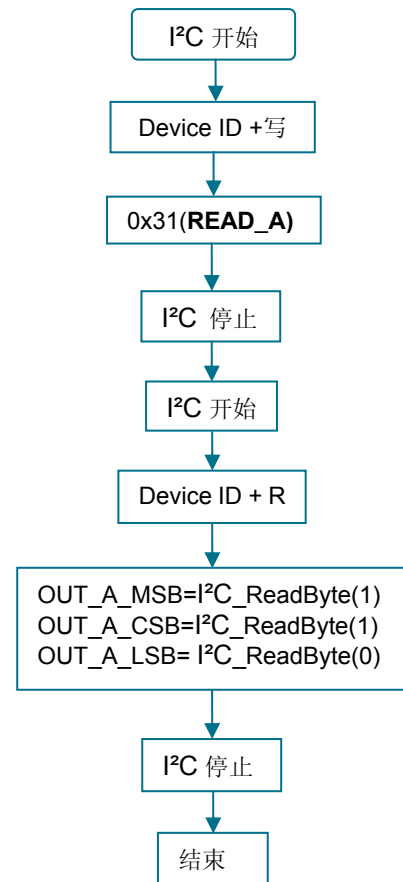
流程图



读取温度和压力值



读取高度值



Notes: **HP206C**

Device ID: 0xEC(write) and 0xED(read).

HP206C 压力传感器焊接注意事项:

1. 产品可以在 250℃温度下 40 秒之内进行标准回流焊接。为避免对传感器敏感元件造成损坏，要求焊接温度尽量低，且受热时间也尽量短，所以请选用低温焊锡。
2. HP206C 要求用 SMT 贴片，并且贴片后，需要放置 5~7 天时间恢复到稳定状态。因为受热及贴装的拉力会导致产品中传感器晶片受力不均，感应大气压力的稳定性就受到影响。
3. 不建议手工焊接，因为无法保证时间、温度高低、温度受热的均匀度，以及焊盘上锡的厚度不一致。在同一块板上，焊接其它元件时也会间接让传感器瞬间受热不均。这些因素都会导致传感器性能下降或损坏。
4. 不可以带电焊接，做好防静电的措施。

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